VECTORBORD®

3797-2 2.73" x 4.5" **Circuit Pattern:** 3-Hole Solder Pad Contacts: 15/30 @ .156" Ctrs, 3-hole solder pads (0.28" x Ni/Gold 0.080") for interconnecting Width/Thick: 4.50"/.062" multiple component leads Height: 2.73" ces solder-16-Pin DIP Capacity: enience Material: read hole Wire-Wrap Terminals: iring side Wire-Wrap Socket Pins: tructions Solder Connector:

2

3690-8

R644-2

.042"

Series 12

4.5" x 4.5"

Contacts Only

Circuit Pattern: Contacts:
Width/Thick:
Height:
16-Pin DIP Capacity:
Material:
Wire-Wrap Terminals:
Wire-Wrap Socket Pins:
Solder Connector:
Extender:
Rec. Card Cage:
Wire-Wrap Connector:
Hole Diameter:

3662-5

Extender: Rec. Card Cage: Hole Diameter:

3795

Circuit Pattern: Contacts:

- Width/Thick: Height: 16-Pin DIP Capacity: Material: Wire-Wrap Terminals: Wire-Wrap Socket Pins: Solder Connector: Extender: Rec. Card Cage: Wire-Wrap Connector: Hole Diameter:
- 22/44 @ .156" Ctrs, Ni/Gold 4.50"/.062" 4.50" 40 CEM-1 T44, T46, T49, T68 R32 R644 3690 Series 13 R644-3 .042"

4.5" x 4.5"

Zig-Zag Buses

Ni/Gold

4.50"

CEM-1

R32

R644

3690

Series 13

R644-3

.042"

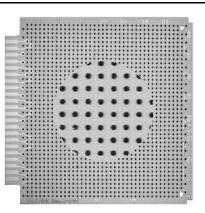
8

4.50"/.062"

22/44 @ .156" Ctrs,

T44, T46, T49, T68

- 22 numbered edge contacts on front side: 21 plus grounding contact on reverse side Bare board provides for unrestricted component placement over entire board surface Hole marking legend on both
- sides of board Layout paper and instructions included

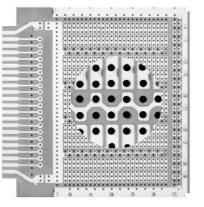


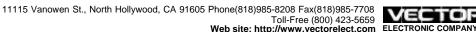
4112-5

Circuit Pattern: Contacts:

Width/Thick: Height: 16-Pin DIP Capacity: Material: Wire-Wrap Terminals: Wire-Wrap Socket Pins: Solder Connector: Extender: Rec. Card Cage: Wire-Wrap Connector: Hole Diameter:

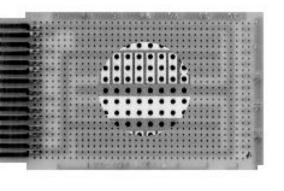
- 3-hole solder pad pattern on wiring side; ground plane on component side with 0.085" diameter, clearance areas around holes 3-hole solder pads (0.028" x
- 0.080" for interconnecting multiple component leads
- · To commit wire-wrap pins to ground planes, use Vector T124 solder washers, available separately
- Layout paper and instructions included
- · Row and column legend provided
- Ground Plane/3-Hole Solder Pad with Zig-Zag Buses







4 CEM-1 T44, T46, T49, T68 R32 R630 3690-10 Series 12 .042"	All pad and bus surfaces sola coated for user convenience Convenient, easy-to-read ho marking legend on wiring sia Layout paper and instruction included
73" x 4.5 Contacts Only 22/44 @ .156" Ctrs Ni/Gold 4.50"/.062" 2.73" 15 CEM-1 T44, T46, T49, T68 R32 R630	 Unrestricted component placement over entire boa surface Accepts virtually any type component Row and column legend provided Layout paper and instructi



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